104363-2 - ACTIVE

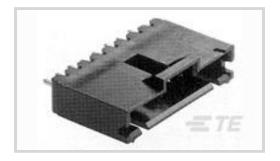
AMPMODU | AMPMODU MTE

TE Internal #: 104363-2 PCB Mount Header, Vertical, Wire-to-Board, 3 Position, .1 in [2.54 mm] Centerline, Fully Shrouded, Gold, Through Hole - Solder, Signal, AMPMODU MTE

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Connectors > PCB Connectors > PCB Headers & Receptacles



Connector System: Wire-to-Board

Number of Positions: 3

Number of Rows: 1

Centerline (Pitch): 2.54 mm [.1 in]

PCB Mount Orientation: Vertical

Features

Product Type Features

Connector System	Wire-to-Board
Header Type	Fully Shrouded
Sealable	No

PCB Connector Assembly Type PCB Mount Header Configuration Features Sumber of Positions Number of Positions 3 Number of Rows 1
Number of Positions 3
Number of Rows 1
PCB Mount Orientation Vertical
Electrical Characteristics
Termination Resistance 15 mΩ
Insulation Resistance 5000 MΩ
Dielectric Withstanding Voltage (Max) 600 V
Body Features
Primary Product Color Black
Contact Features
Contact Mating Area Length 5.84 mm[.23 in]
Mating Square Post Dimension .64 mm[.025 in]

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PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
Contact Mating Area Plating Material Thickness	.381 μm[15 μin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Square
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Brass
Contact Mating Area Plating Material	Gold
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	3.3 mm[.13 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Latched, Polarization
Mating Retention	With
Panel Mount Feature	Without
Mating Retention Type	Polarized Lock

Mating Retention Type	Polarized Lock
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	Without
PCB Mount Retention	Without
Housing Features	
Housing Material	Thermoplastic
Centerline (Pitch)	2.54 mm[.1 in]
Dimensions	
Connector Height	13.59 mm[.535 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	

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Circuit Application	Signal
Industry Standards	
CSA Rating	Certified
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	52
Packaging Type	Box, Tube
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Out of Scope
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2022 (223) Candidate List Declared Against: JUL 2021 (219) SVHC > Threshold:

Halogen Content

Solder Process Capability

Pb (13% in Component Part)

Article Safe Usage Statements:

Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

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Also in the Series | AMPMODU MTE



Standard Rectangular Connectors(2)

Wire-to-Board Connector Assemblies & Housings(585)

Wire-to-Board Connector Contacts(32)

Customers Also Bought



PCB Mount Header, Vertical, Wire-to-Board, 3 Position, .1 in [2.54 mm] Centerline, Fully Shrouded, Gold, Through Hole - Solder, Signal, AMPMODU MTE



Documents

CAD Files 3D PDF

3D

Customer View Model

ENG_CVM_CVM_104363-2_W.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_104363-2_W.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_104363-2_W.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages AMPMODU MTE INTERCONNECT SYSTEM

English

Product Specifications

Application Specification

English

Product Environmental Compliance

Product Compliance

English

Product Compliance

English

Instruction Sheets Instruction Sheet (U.S.)

English